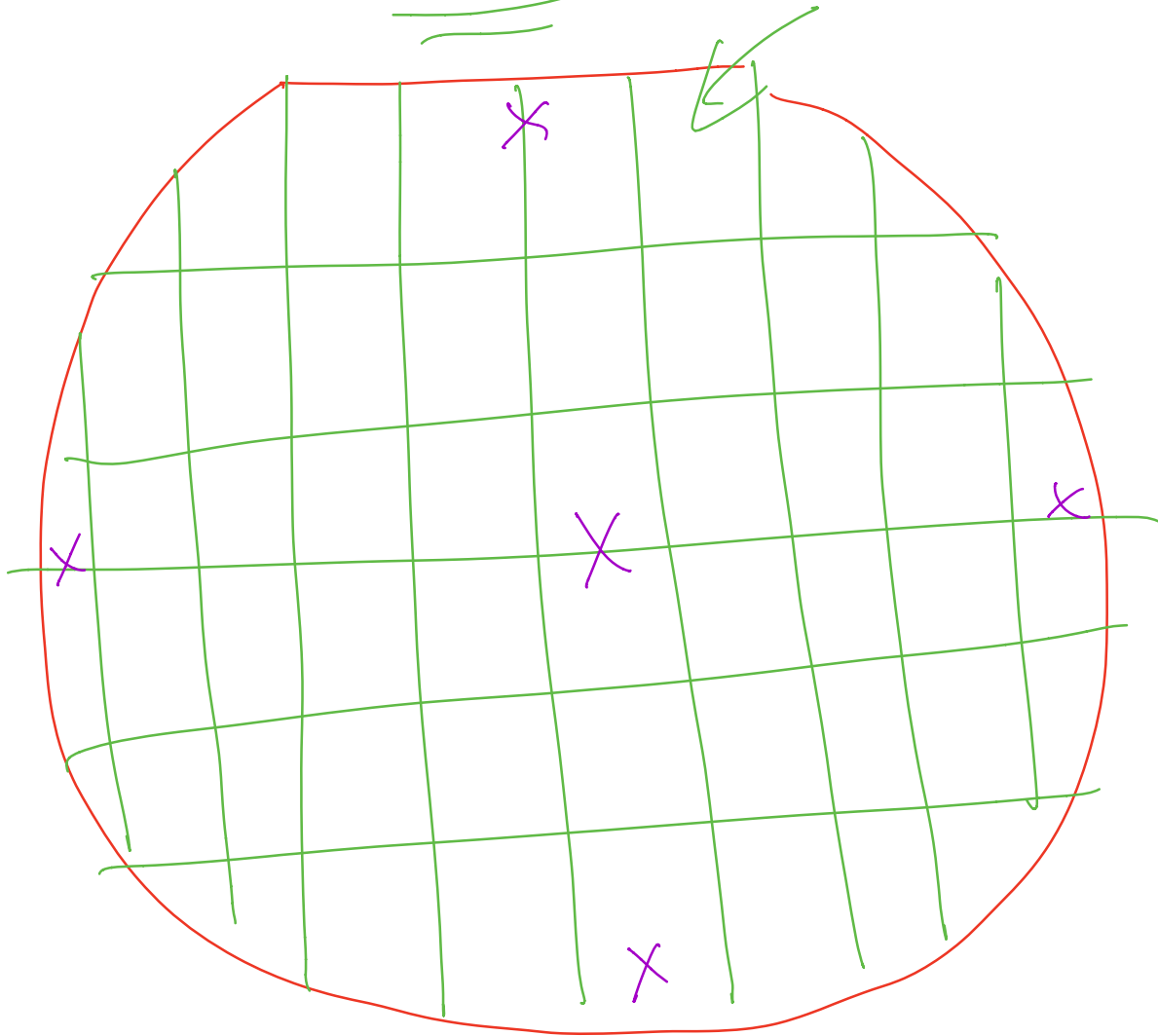


QP test → 52 dies



Questions for Mark

1) what is the blade thickness on the wafer saw that you use?

2) 4" vs 3" → it's all Si


3) Au ribbons!

ends

C D

1 cm<sup>2</sup> devices

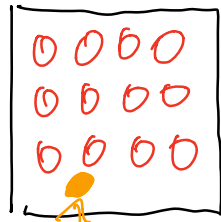
make compatible w/ Au wire bond thermal link

1)  ← 2 channel devices that allow for G<sub>ab</sub> testing!



52 → 1 cm<sup>2</sup>

1 TES & 1 QES

single channel TES devices

2)  ← 1 cm<sup>2</sup> devices with a variety of covers

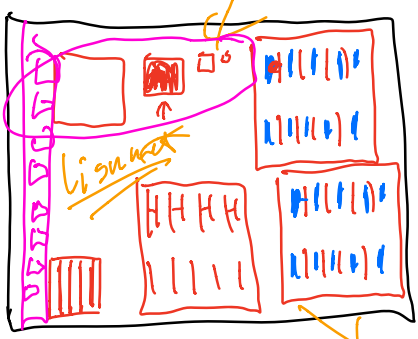
make all devices compatible with Au wire bond deposition

- 1) 50% coverage [for placement in superfluid He] ✓
- 2) 40% coverage → 
- 3) 10% coverage → 
- 4) 25% coverage → this device needs to not be homogeneous
- 5) 0.1% coverage → this device needs to not be homogeneous
- 6) just a TES device
  - is the 2<sup>nd</sup> full time seen in CPD vol due to absorption by TES 4%

3) TES noise chips

6

gold



- 1) standard 4 TES series for parasitic noise
- 2) TES series to measure G<sub>ep</sub> and noise of Finconnectors use the 100 x 400 as the base!
- 3) this may need to be 2 hrs

of different  
size!

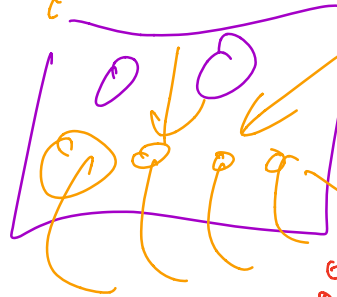
4) 2 QET channels (2 devices)  
 $\Rightarrow$  4% coverage

(41)

160 x 640  
 80 x 320  
 40 x 160  
 20 x 80  
 20 x 40  
 20 x 20

5) Measuring 6 gold  $Q_h$  x 5

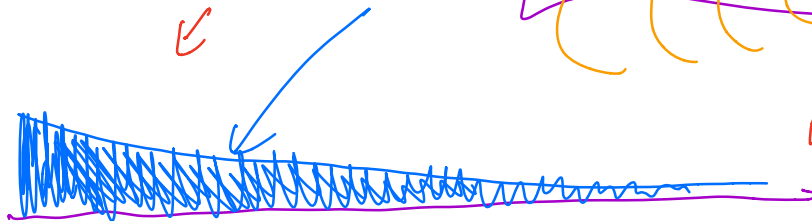
(2)

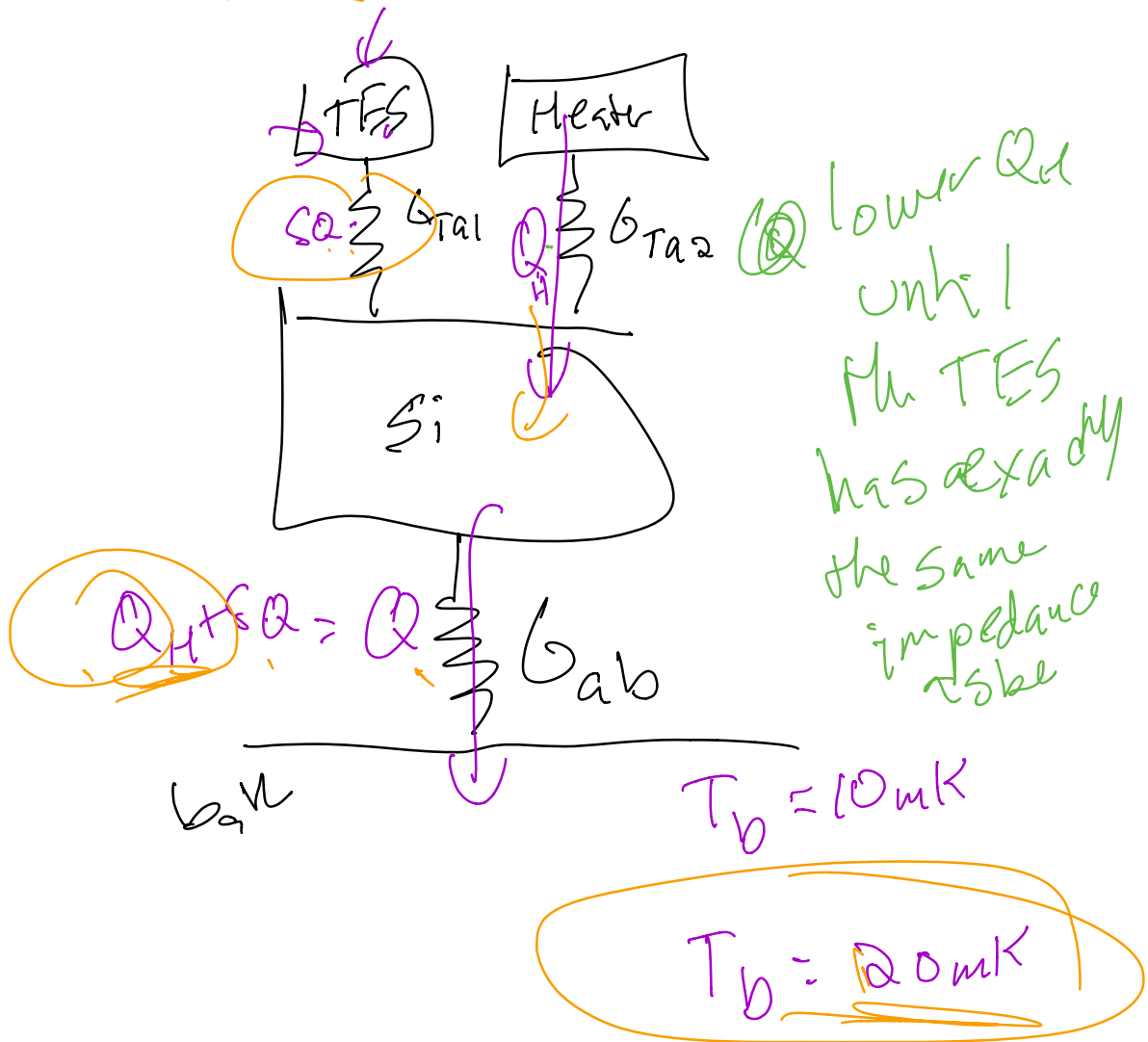
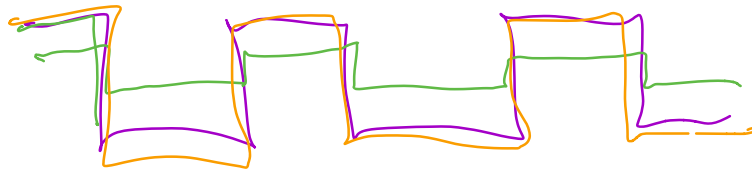


200  
 7  
 200

56 x 100

500  
 100  
 100  
 +  
 wire  
 board





$$P_{\text{joule}} = P_{\text{cool}} = \sum V (T^n - T_a^n)$$

$\frac{V_B^2}{R} \Rightarrow$

$$\underline{Q_H} = \cancel{\infty} T_a^M - \underline{T_b^M}$$

